

HUGE Automations. CO.,LTD

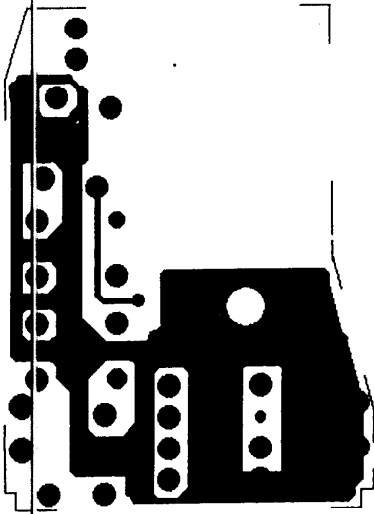
Bill of Material File

Typ HSC-1671

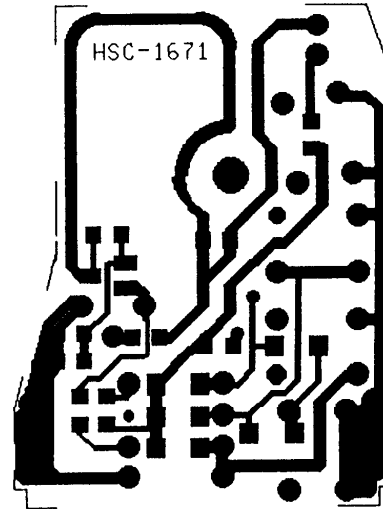
No.	Package	Description	Quantity	Designator	Level
1	DIP	PCB HSC-1671	1		1
2	SMD	Capactor SMD 102K 0805	1	C3	4
3	SMD	Capactor SMD 1PJ 0805	1	C1	4
4	SMD	Capactor SMD 3PJ 0805	1	C2	4
5	SMD	Diode SMD LL4148	5	D1-5	4
6	SMD	Resistor SMD 100R 0805	1	R3	4
7	SMD	ResistorSMD 47R 0805	2	R1,4	4
8	SMD	Resistor SMD 47K 0805	1	R2	4
9	SMD	TR SMD 2SC3838KQ	1	Q1	4
10	DIP	Micell 3.6mm	1	LED1	3
11	DIP	IC HCS200/P SAW	1	U1	3
	DIP	LED 3mm (M034PD)	1	LED1	3
13	DIP	Spring +	1	+	3
14	DIP	Spring -	1	-	3
15	DIP	TACT SW TSAB-3 6*6*5mm 260	4	K1-4	3
16	DIP	SAW SRU434RAF(433.92M DIP)	1	TOSHIBA	3
17	Assembly	HRC-710 case	1		2
18	Assembly	HRC-710 rubber key	1		2
19	Assembly	Batty V-23A 12V	1		2
20	Assembly	KEY CHAIN #107	1		2
21	Assembly	Screw 2.0*8	1		2
22	Assembly	Screw 2.3*9	1		2

SENTON GmbH
 EMV-Prüfzentrum
 Außere Frühlingsstraße 45
 D-94315 Straubing
 Telefon 09421/5522-0

HSC-1671



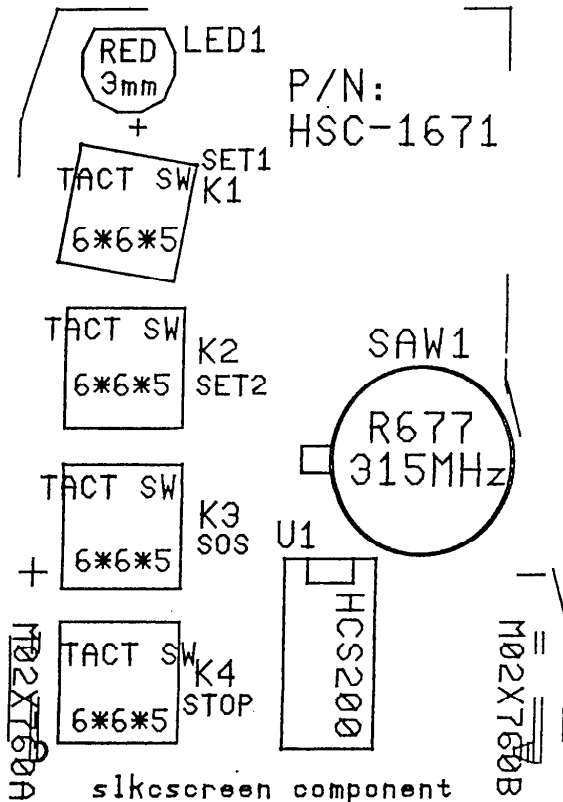
Component Copper



solder copper

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HSC-1671 DIP PARTS 插件图



MHz	SAW1	C1	C2	
303	R658			
315	R677	4PF	15PF	
318				
418				
434	R670	1PF	3PF	

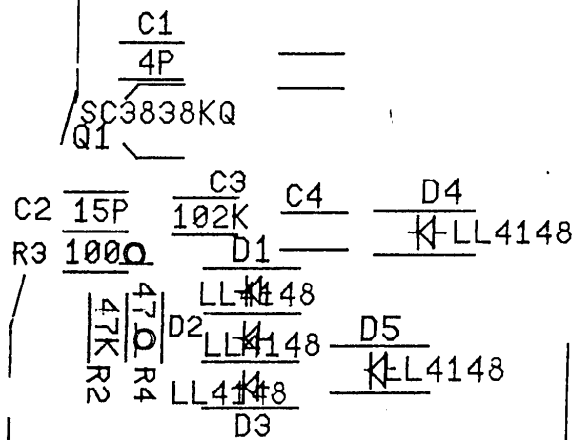
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C7

HSC-1671 SMD PARTS 插件图

※未标示数值者不插

R1



silkscreen solder

	C2	C1	SAW1	MHz
			R658	303
	15PF	4PF	R677	315
				318
				418
	3PF	1PF	R670	434

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